## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

**Serial No.:** 09/944,015

Filed: August 30, 2001

**For:** PLASTIC LEAD FRAMES FOR SEMICONDUCTOR DEVICES (amended)

Confirmation No.: 9929

Examiner: A. Chambliss

**Group Art Unit: 2827** 

Attorney Docket No.: 2269-3086.7US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

February 10, 2003

Date

Deidra Pfeil

Signature

Name (Type/Print)

## LETTER TO THE CHIEF DRAFTSMAN

Box Issue Fee Commissioner for Patents Washington, D.C. 20231

Sir:

Applicant submits herewith revised FIGS. 6 and 7 which correct errors in the drawings. Specifically, FIG. 6 has been revised to delete the reference numeral "200" with appropriate lead line; and FIG. 7 has been revised to delete the reference numeral "300" with appropriate lead line. Attached is a copy of the drawings with the proposed changes marked in red.

No new matter has been added. Approval of the proposed revisions is respectfully requested.

Respectfully submitted,

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JRD/djp

Enclosures: Drawings with changes marked in red

Document in ProLaw



Tongbi Jiang et al.
Serial No. Not yet assigned
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Attorney Docket No. 3086.7US
Sheet 4 of 4
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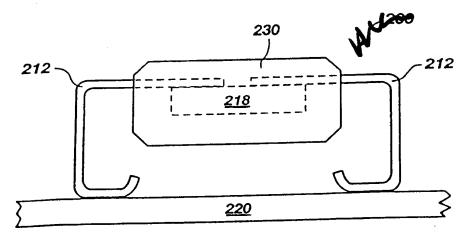


Fig. 6

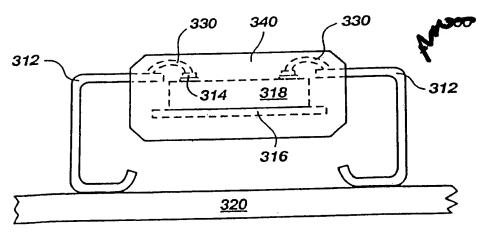


Fig. 7